

MA3SE01

Silicon epitaxial planar type

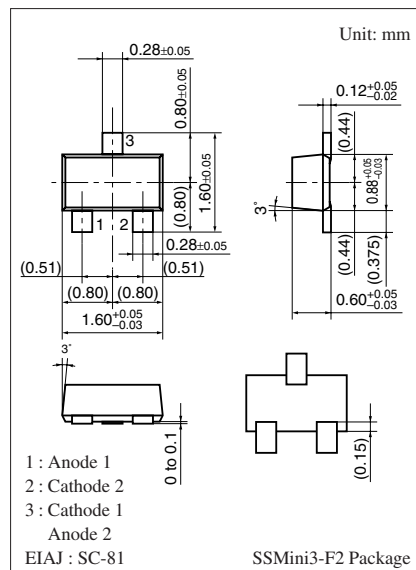
For cellular phone

■ Features

- High-frequency wave detection is possible
- Low forward voltage V_F
- Small junction-capacitance

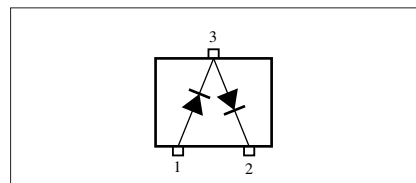
■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|------------------------------|-----------|-------------|------------------|
| Reverse voltage | V_R | 20 | V |
| Maximum peak reverse voltage | V_{RM} | 20 | V |
| Forward current | Single | I_F | mA |
| | Series | | |
| Peak forward current | Single | I_{FM} | mA |
| | Series | | |
| Junction temperature | T_j | 125 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -55 to +125 | $^\circ\text{C}$ |



Marking Symbol: M6A

Internal Connection

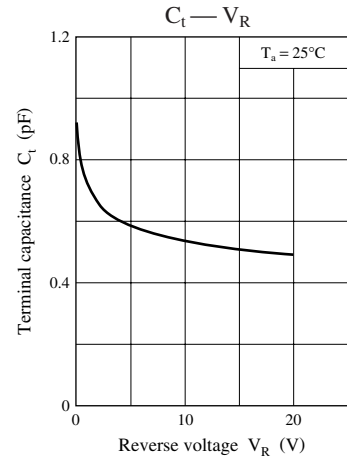
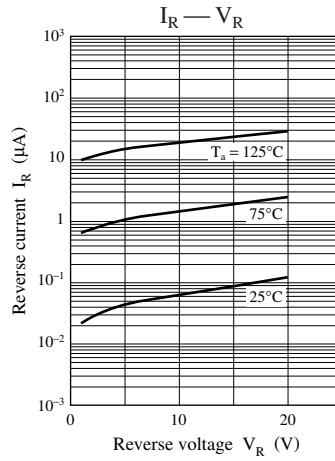
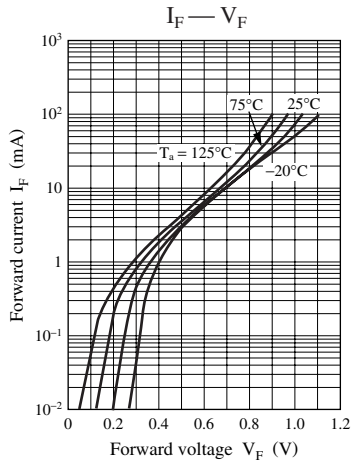


■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|----------------------|----------|--|-----|-----|------|----------|
| Forward voltage | V_{F1} | $I_F = 1 \text{ mA}$ | | | 0.41 | V |
| | V_{F2} | $I_F = 35 \text{ mA}$ | | | 1.0 | V |
| Reverse current | I_R | $V_R = 15 \text{ V}$ | | | 200 | nA |
| Terminal capacitance | C_t | $V_R = 0 \text{ V}, f = 1 \text{ MHz}$ | | | 1.2 | pF |
| Dynamic resistance | R_d | $I_F = 5 \text{ mA}$ | | 40 | | Ω |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 2 GHz



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